

**Preliminary Amendment**

Applicant: Melissa D. Boyd et al.

Serial No.: Unknown (Parent Serial No. 10/194,843)

Filing Date: Herewith (Parent Filing Date: July 11, 2002)

Docket No.: 10970792-4

Title: MULTILAYERED CERAMIC SUBSTRATE SERVING AS INK MANIFOLD AND ELECTRICAL INTERCONNECTION PLATFORM FOR MULTIPLE PRINTHEAD DIES (as originally filed)

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**IN THE SPECIFICATION**

Please amend the CROSS REFERENCE TO RELATED APPLICATIONS as follows:

delete page 1, lines 2-4 and insert the following:

-- This is a Continuation of co-pending U.S. Patent Application Serial No. 10/194,843, filed on July 11, 2002, which is a Continuation of U.S. Patent Application Serial No. 09/972,648, filed on October 5, 2001, now U.S. Patent No. 6,435,653, which is a Continuation of U.S. Patent Application Serial No. 09/216,606, filed on December 17, 1998, now U.S. Patent No. 6,322,206, which is a Continuation-in-Part of U.S. Patent Application Serial No. 08/959,376, filed on October 28, 1997, now U.S. Patent No. 6,123,410, each assigned to the assignee of the present invention and incorporated herein by reference. --

Please amend the SUMMARY OF THE INVENTION as follows:

delete page 2, line 26 - page 4, line 17 (all inclusive) and insert the following:

-- One aspect of the present invention provides a fluid ejection assembly. The fluid ejection assembly includes a platform having a fluid inlet, a fluid outlet, a plurality of fluid feed slots, and a fluid manifold defined therein, and a plurality of fluid ejection devices each mounted on the platform and including an array of drop ejecting elements and a fluid refill slot communicating with the array of drop ejecting elements. The fluid refill slot of each of the fluid ejection devices communicates with at least one of the fluid feed slots of the platform, and the fluid manifold of the platform fluidically couples each of the fluid feed slots with the fluid inlet and the fluid outlet of the platform. --